

INFORMATION DISCLOSURE STATEMENT BY APPLICANT

(Multiple sheets used when necessary)

SHEET 1 OF 3

Application No.	10/826,219
Filing Date	April 16, 2004
First Named Inventor	Homayoun Talieh
Art Unit	1742
Examiner	Unknown
Attorney Docket No.	ASMNUT.037C5

U.S. PATENT DOCUMENTS

Examiner Initials	Cite No.	Document Number	Publication Date	Name of Patentee or Applicant	Pages, Columns, Lines Where Relevant Passages or Relevant Figures Appear
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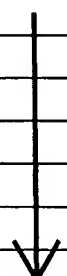
Examiner Signature /Lois Zheng/

Date Considered 03/19/2007

*Examiner: Initial if reference considered, whether or not citation is in conformance with MPEP 609. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

T¹ - Place a check mark in this area when an English language Translation is attached.

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(Multiple sheets used when necessary)	Examiner	Unknown
SHEET 2 OF 3	Attorney Docket No.	ASMNUT.037C5

U.S. PATENT DOCUMENTS					
Examiner Initials	Cite No.	Document Number	Publication Date	Name of Patentee or Applicant	Pages, Columns, Lines Where Relevant Passages or Relevant Figures Appear
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Examiner Initials	Cite No.	Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume-issue number(s), publisher, city and/or country where published.	T ¹
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Examiner Signature	/Lois Zheng/	Date Considered	03/19/2007
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NON PATENT LITERATURE DOCUMENTS			
Examiner Initials	Cite No.	Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume-issue number(s), publisher, city and/or country where published.	T ¹
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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of: Talieh et al. Serial No.: 10/459,321 Filed: June 10, 2002 Title: Device Providing Electrical Contact To The Surface Of A Semiconductor Workpiece During Processing	Group Art Unit: Not yet assigned Examiner: Not yet assigned Docket: NT-105C5-US
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INFORMATION DISCLOSURE STATEMENT

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Examiner Initials	Cite No.			Translation
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/LZ/		Joseph M. Steigerwald et al., "Chemical Mechanical Planarization of Microelectronic Materials", A Wiley-Interscience Publication, 1997 by John Wiley & Sons, Inc. pages 212-222	In related S/N 09/685,934	

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